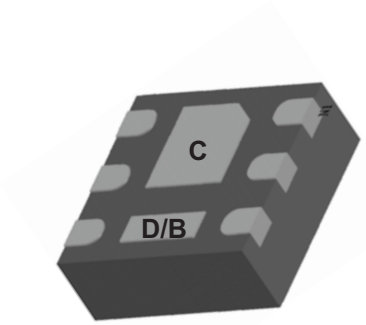
WPT2N31

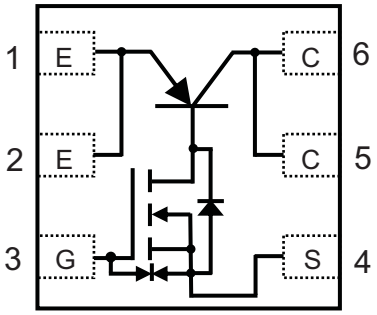
Single, PNP, -30V, -3A, Power Transistor with 20V N-MOSFET

Descriptions

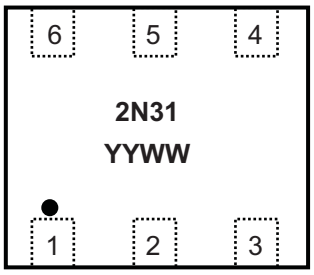
The WPT2N31 is PNP bipolar power transistor with 20V N-MOSFET. This device is suitable for use in charging circuit and other power management. Standard Product WPT2N31 is Pb-free.



DFN2x2-6L



Pin configuration (Top view)



2N31 = Device code
YY = Year
WW = Week
Marking

Features

- Ultra low collector-to-emitter saturation voltage
- High DC current gain >100
- 3A continue collector current
- Small package DFN2x2-6L

Applications

- Charging circuit
- Other power management in portable equipments

Order information

Device	Package	Shipping
WPT2N31-6/TR	DFN2x2-6L	3000/Reel&Tape

Absolute maximum ratings

Parameter	Symbol	Value	Unit
PNP Transistor			
Collector-emitter voltage	V_{CEO}	-30	V
Collector-base voltage	V_{CBO}	-30	V
Emitter-base voltage	V_{EBO}	-6	V
Continues collector current [a]	I_C	-3	A
Continues collector current [b]		-2	A
Pulse collector current [c]	I_{CM}	-6	A
N-MOSFET			
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	±6	V
Continuous Drain Current [a]	I_D	0.80	A
Continuous Drain Current [b]		0.69	A
Pulsed Drain Current [c]	I_{DM}	1.4	A
Power Dissipation and temperature			
Power dissipation [a]	P_D	1.2	W
Power dissipation [b]		0.8	W
Junction Temperature	T_J	150	°C
Lead Temperature	T_L	260	°C
Operation Temperature	T_A	-40 ~ 85	°C
Storage Temperature Range	T_{stg}	-55 to 150	°C

Thermal resistance ratings

Parameter	Symbol	Value	Unit
Junction-to-Ambient Thermal Resistance [a]	$R_{\theta JA}$	104	°C/W
Junction-to-Ambient Thermal Resistance [b]	$R_{\theta JA}$	155	°C/W

a Surface mounted on FR-4 Board using 1 square inch pad size, 1oz copper

b Surface mounted on FR-4 board using minimum pad size, 1oz copper

c Pulse width=300μs, Duty Cycle<2%

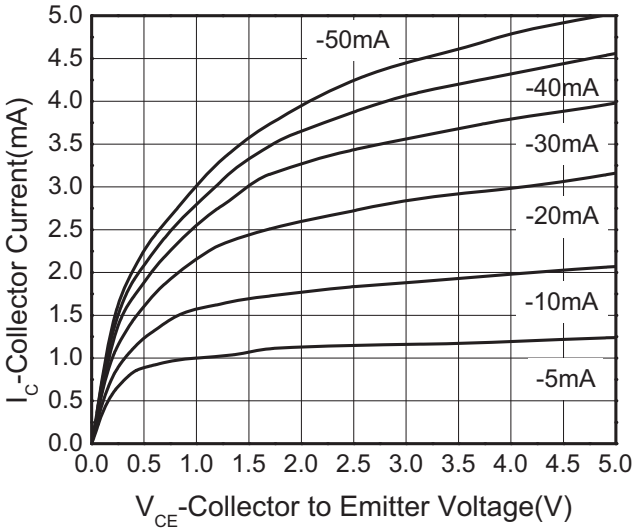
d Maximum junction temperature T_J=150°C.

Electronics Characteristics (Ta=25°C, unless otherwise noted)

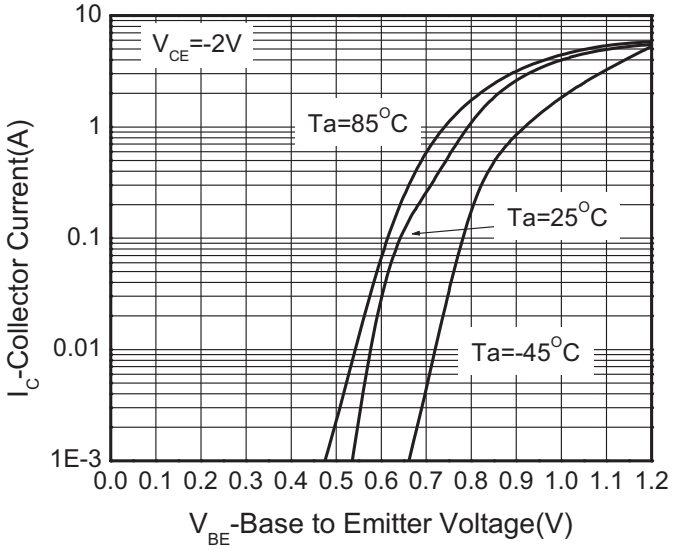
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
PNP Transistor						
Collector-emitter breakdown voltage	BV_{CEO}	I_C=-10mA, I_B=0mA	-30			V
Collector-base breakdown voltage	BV_{CBO}	I_C=-1mA, I_E=0mA	-30			V
Emitter-base breakdown voltage	BV_{EBO}	I_E=-100uA, I_C=0mA	-6			V
Collector cutoff current	I_{CBO}	V_{CB}=-30V			-100	nA
Emitter cutoff current	I_{EBO}	V_{EB}=-5V			-100	nA
Collector-emitter saturation voltage	$V_{CE(sat)}$	I_C=-2A, I_B=-200mA		-0.2	-0.4	V
Base-emitter saturation voltage	$V_{BE(sat)}$	I_C=-2A, I_B=-200mA		-1.0	-1.5	V
Base-emitter forward voltage	$V_{BE(on)}$	I_C=-0.5A, V_{CE}=-2V		-0.7	-1.0	V
DC current gain	h_{FE}	VCE=-2V,IC=-1A	100		300	
N-MOSFET						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=250uA	20			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=20V, V_{GS}=0V			1	uA
Gate –Source leakage current	I_{GSS}	V_{DS}=0V, V_{GS}=±5V			±5	uA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}= V_{GS}, I_D=250uA	0.45	0.55	1.0	V
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}=4.5V, I_D=0.55A		220	260	mΩ
		V_{GS}=2.5V, I_D=0.45A		260	310	mΩ
		V_{GS}=1.8V, I_D=0.35A		320	380	mΩ
		V_{GS}=1.5V, I_D=0.10A		600	1100	mΩ
Input Capacitance	Ciss	V_{DS}=10V, V_{GS}=0V, F=1Mhz		50		pF
Output Capacitance	Coss			13		pF
Reverse Transfer Capacitance	Crss			8		pF
Total Gate Charge	$Q_{G(TOT)}$	V_{DS}=10V, V_{GS}=4.5V, I_D=0.6A		1.15		nC
Threshold gate charge	$Q_{G(TH)}$			0.06		nC
Gate-Source Charge	Q_{GS}			0.15		nC
Gate-Drain Charge	Q_{GD}			0.23		nC
Turn-On Delay Time	td(on)	V_{DD}=10V, V_{GS}=4.5V, I_D=0.5A, R_L=10Ω, R_G=6Ω		22		ns
Turn-On Rise Time	tr			80		ns
Turn-Off Delay Time	td(off)			700		ns
Turn-Off Fall Time	tf			650		ns
Body Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=0.35A	0.5	0.7	1.0	V

Typical Characteristics (Ta=25°C, unless otherwise noted)

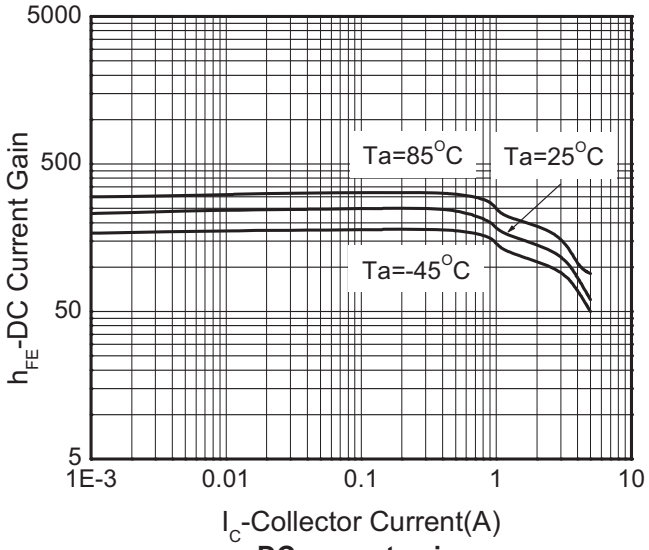
PNP Transistor



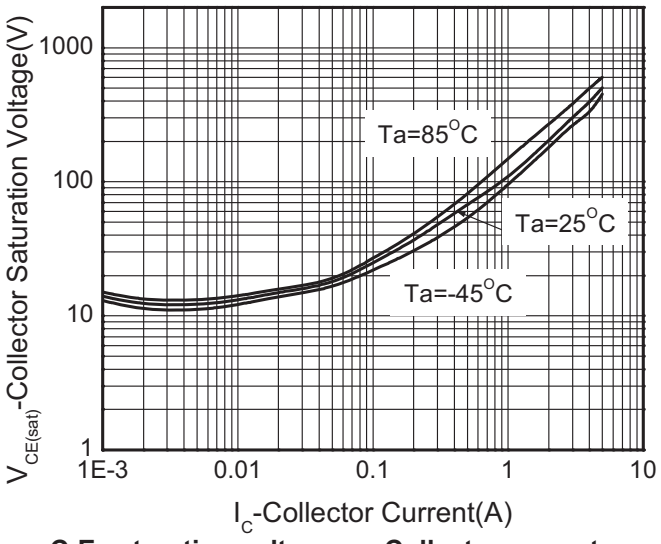
Output characteristics



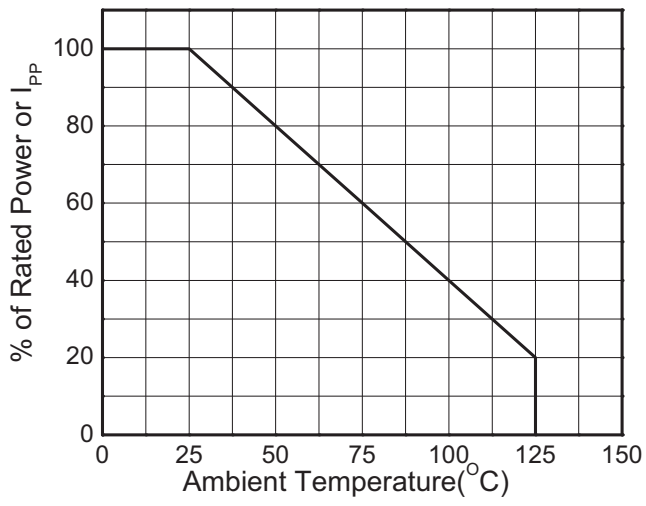
Transfer characteristics



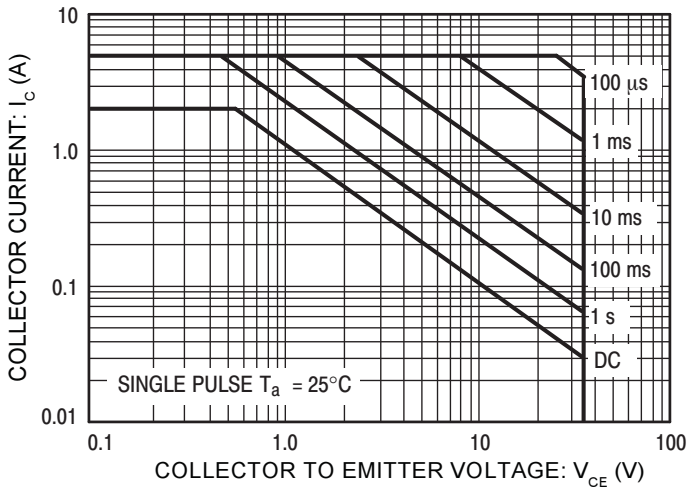
DC current gain



C-E saturation voltage vs. Collector current

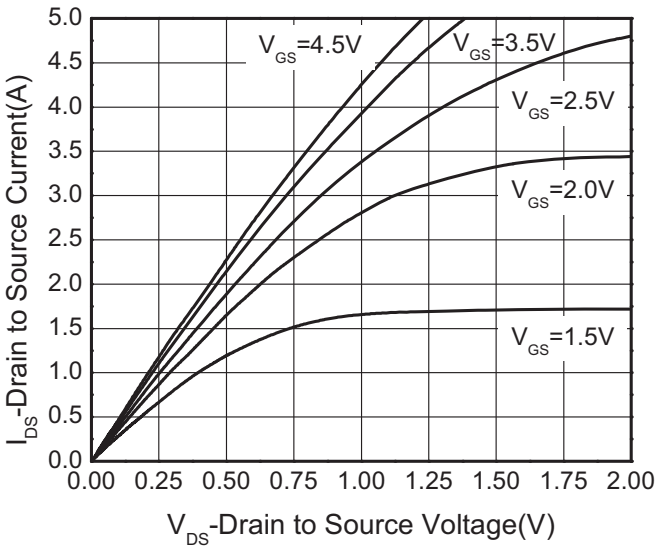


Power Derating

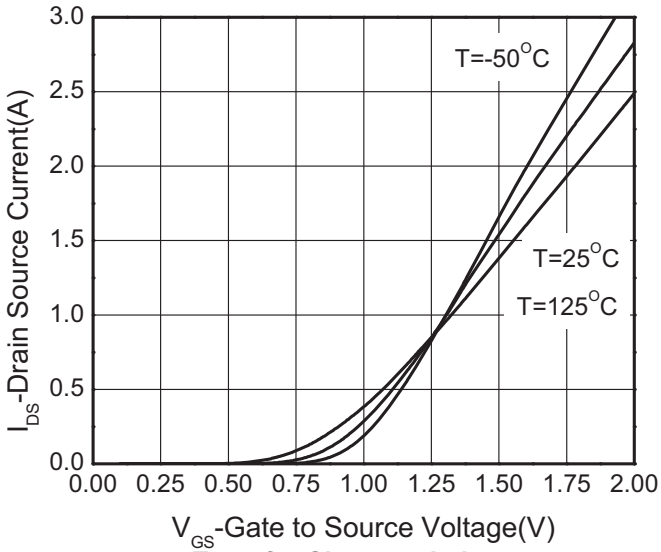


Safe operating area

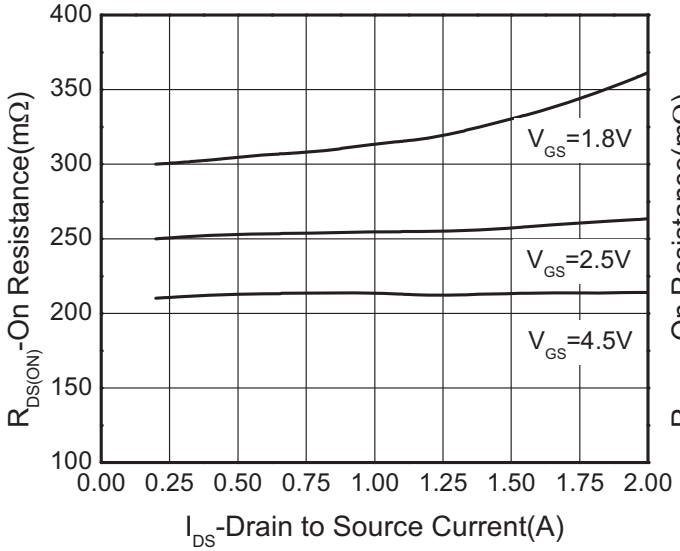
N-MOSFET



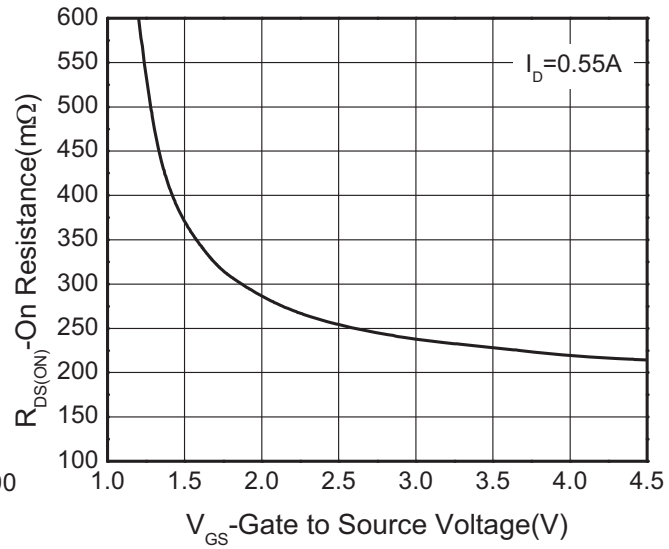
Output Characteristics



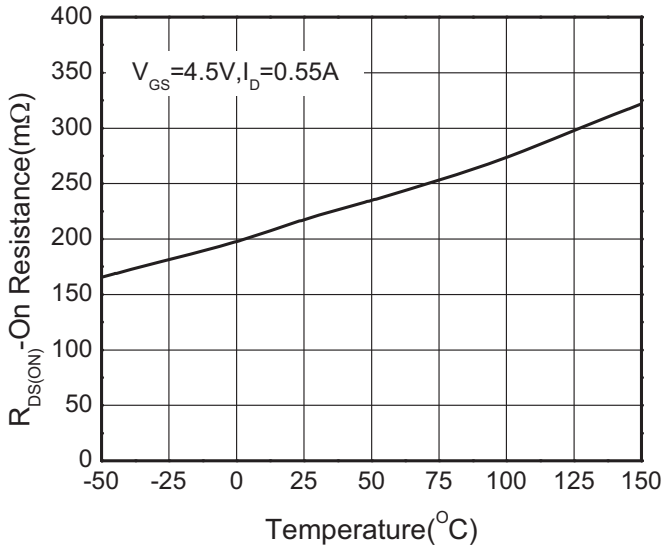
Transfer Characteristics



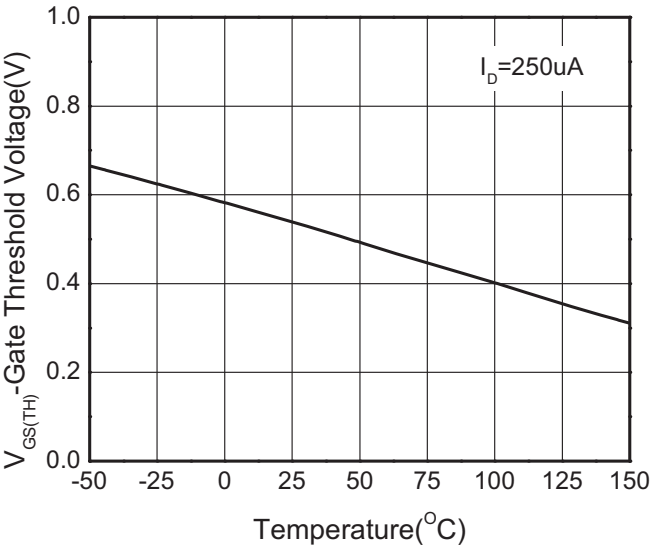
ON Resistance vs. Drain Current



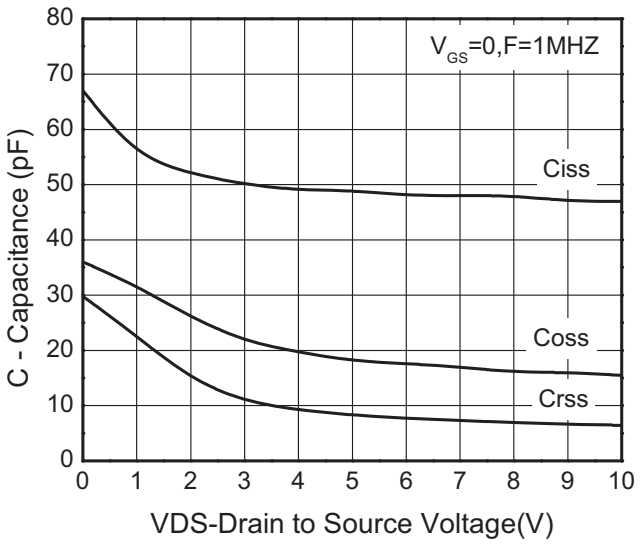
ON Resistance vs. Gate-to-Source Voltage



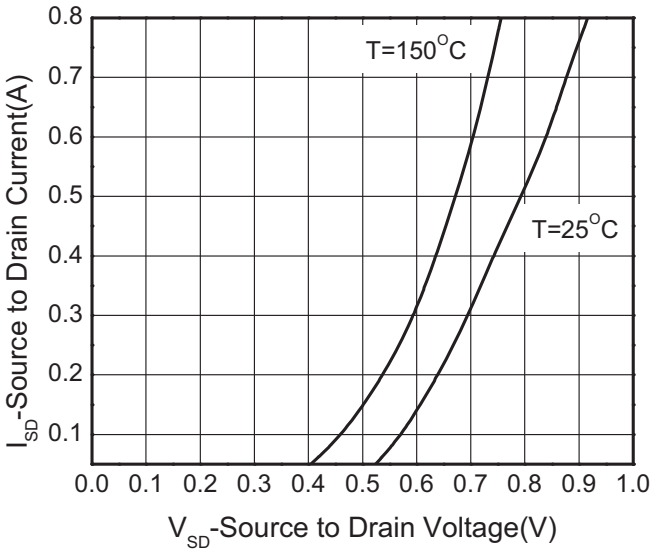
ON Resistance vs. Junction Temperature



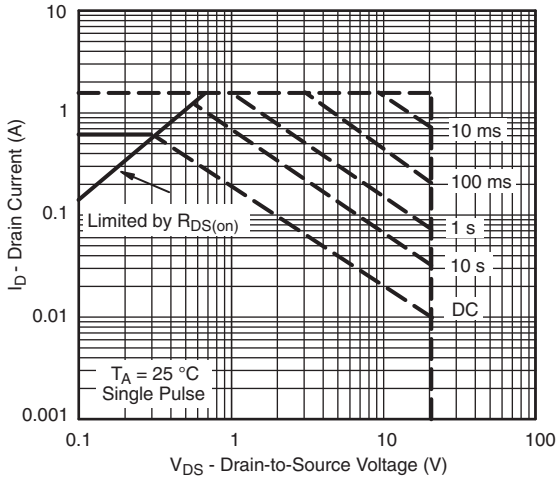
Threshold Voltage vs. Temperature



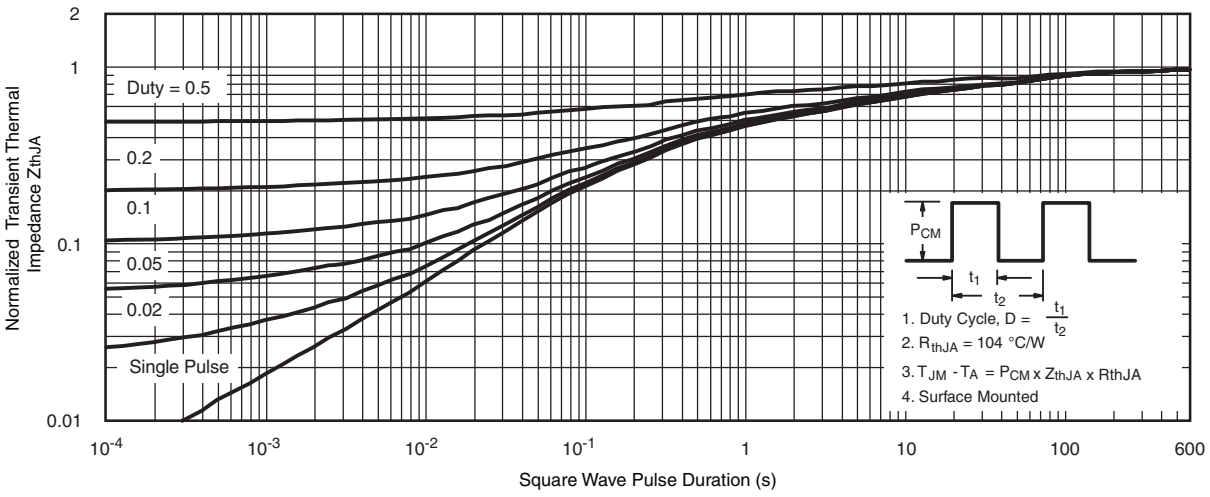
Capacitance



Body Diode Characteristics



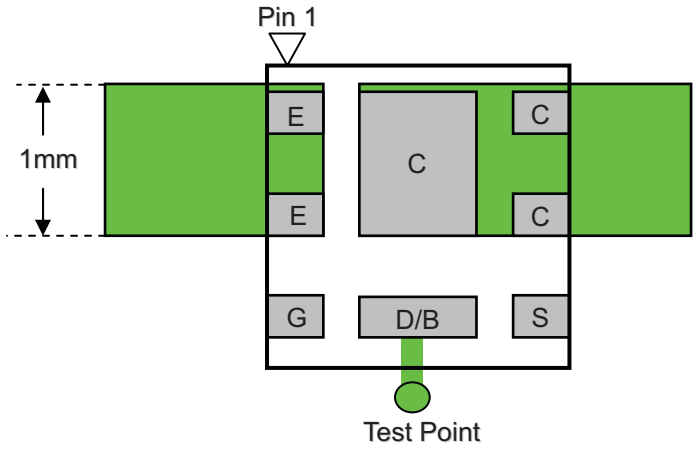
Safe Operation Area



Transient thermal response (Junction-to-Ambient)

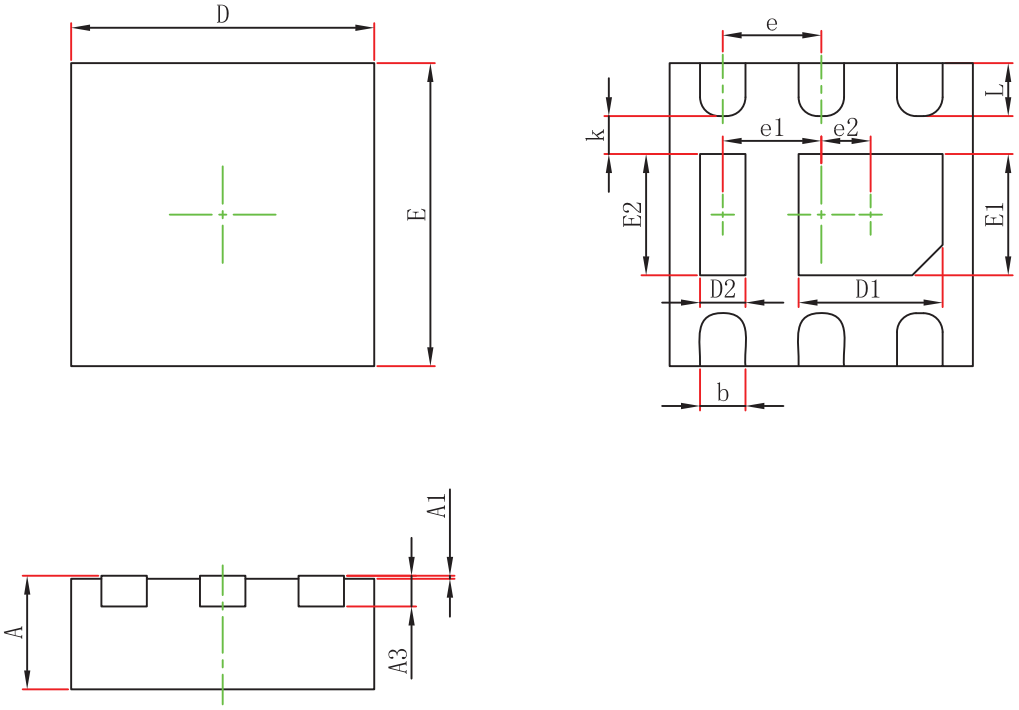
Application note and recommend layout

1. The greater exposed pad of bottom is connected to collector of transistor internally.
2. The smaller exposed pad of bottom is connected to drain of MOSFET and base of transistor internally.
3. Recommend layout as below:



Package outline dimensions

DFN2x2-6L



Symbol	Dimensions In Millimeters		
	Min.	Typ.	Max.
A	0.700		0.800
A1	0.000		0.050
A3	0.203 Ref.		
D	1.924	2.000	2.076
E	1.924	2.000	2.076
D1	0.850	0.950	1.050
E1	0.700	0.800	0.900
D2	0.200	0.300	0.400
E2	0.700	0.800	0.900
e1	0.650 Typ.		
e2	0.325 Typ.		
k	0.200 Min.		
b	0.250	0.300	0.350
e	0.650 Typ.		
L	0.300	0.350	0.400